

威达诚实业有限公司 WEIDACHENG INDUSYRY CO., LTD

SOLDERING PLACEMENT' SYSTEM 锡球植入机-BU-560

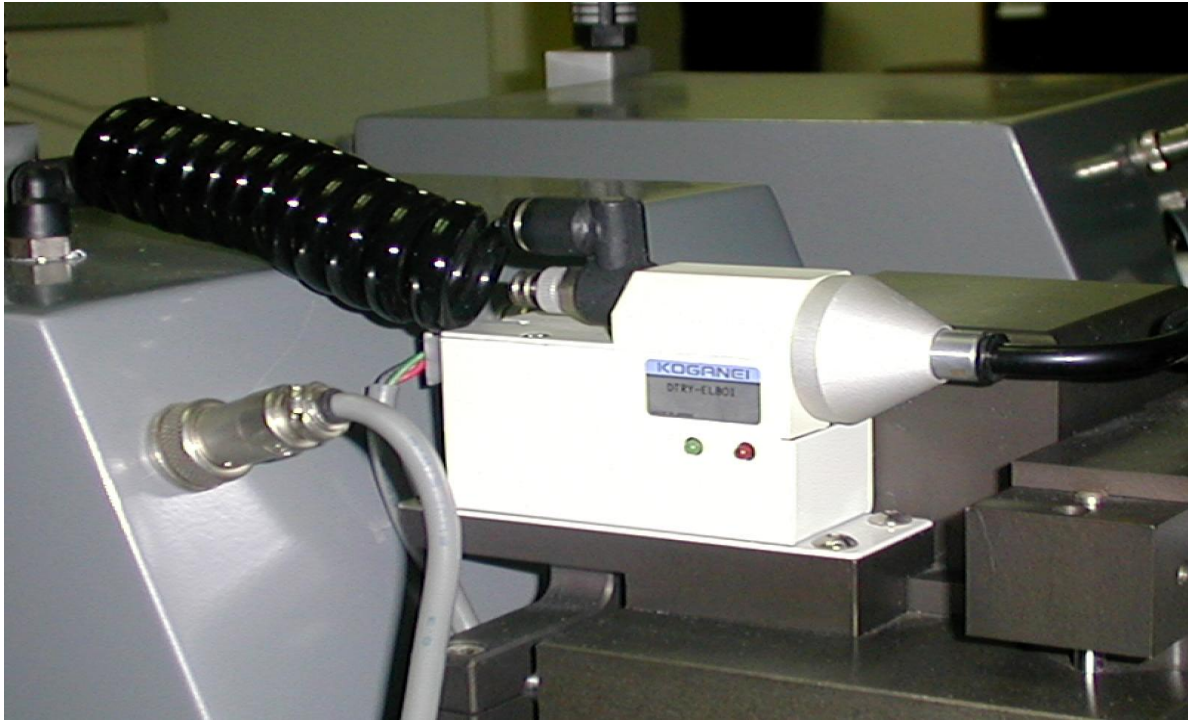
植球能力:  $0.35\Phi\sim0.76\Phi$  植球范围:L-60mm .W-80mm



X. Y.  $\theta$  分厘卡调整滑座与 BGA-模具



**选购配备**—离子净电消除器(消除锡球带电)



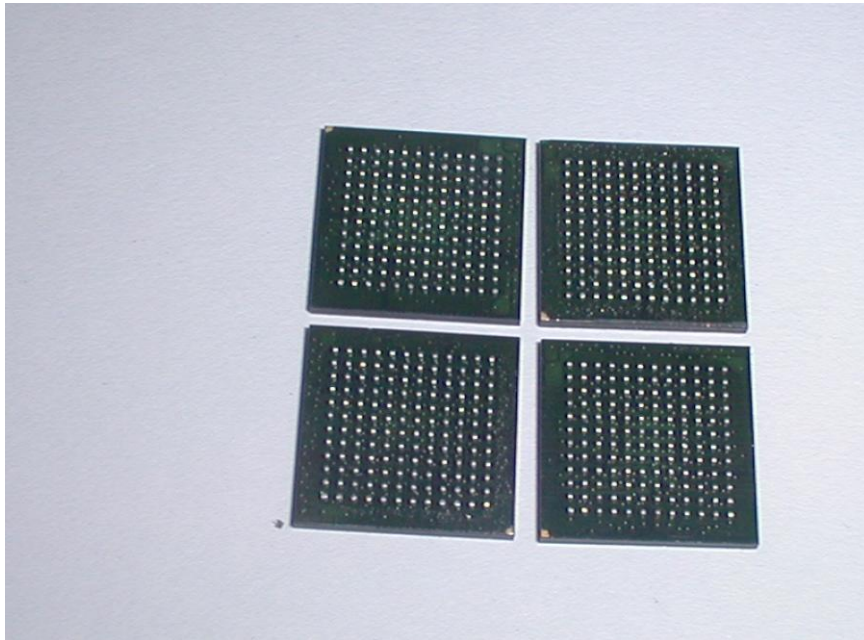
除球收集瓶座(清球配置)



## 卡夹抽取式锡球模具更换座



## 各类 BGA-IC 植球



## 维修设备

## 锡球植入机

BGA rework equipment --- Solder ball placement system BU-560

(1)外部尺寸 :75cm(L),X 25cm(W),X 26cm(H)

■ **Outside dimension: 75cm(L), 25cm(W), 26cm(H).**

(2)重量 : 30.5 kg.

■ **Weight: 30.5 kg.**

(3)使用电压 : 110/220V 50/60Hz.

■ **Working voltage: 110/220V;50/60Hz**

(4)使用气压 : 6 kg/cm<sup>2</sup>.

■ **Working air pressure: 6 kg/cm<sup>2</sup>.**

(5)锡球规格 :依 BGA 不同使用锡球规格而异.

■ **Solder ball specification: According to the solder ball spec being used by different kinds of BGA package.**

(6)BGA 模具 :依 BGA 不同规格 SIZE 可更换需求 BGA 模具.

■ **BGA IC holder: It is available for changing-over different types of BGA IC holders according to different size or spec of BGA package.**

(7) BGA 模具 :依 BGA 不同规格 SIZE 可更换需求锡球模具模具.

■ **Solder ball screening fixture: It is available for changing-over different ball screening fixtures according to different size or spec of solder ball.**

(8)锡球植入速度: 锡球植入 BGA-PAD 点可微调控制锡球植入速度.

■ **Solder ball placing speed: The speed for placing solder balls onto BGA pads can be adjusted and fine-tuning controlled.**

(9)锡球植入率:百分之 98

■ **Ball-placing yield rate: 98%.**

(10)锡球植入精度:0.03 mm.

■ **Ball-placing accuracy: 0.03mm.**

(11)模具槽退料:退料速度 30 - 300 mm/S.

■ **BGA IC holder unloading speed: Unloading speed 30~300 mm/s.**

(12)自动植球时间:22/sec

■ **Automatic ball-placing operation cycle time : 22 seconds.**

## BGA 再造

### BGA regeneration!

### 以低廉锡球 重新植入再造完整

~ Place solder balls on BGA to regenerate a whole new one with the lowest cost. ~

锡球植入机,未拆下 BGA 重新植入全新锡球,以利重新回焊维修,本设备提供 SMT 业界进入 BGA 作业技术层次的提升,本机为 BGA 生产作业得力助手.

The solder ball placement system places new solder balls again onto ball removed BGA-IC for new reflowing rework. This equipment provides a technology promotion for traditional BGA operation in SMT industry. It is a very useful tool for BGA production.

**本设备荣获多国专利仿冒必究**

[There are patents approved by lots of countries for this equipment. All rights are reserved]

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